# **GSM3112SF**

# **30V N-Channel MOSFETs**

#### **Product Description**

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

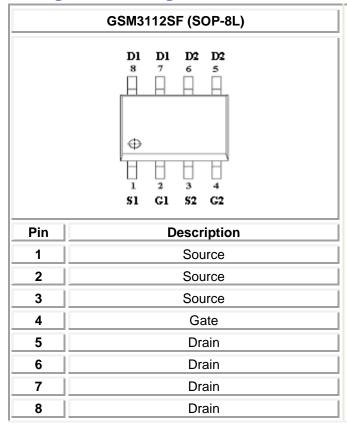
#### **Features**

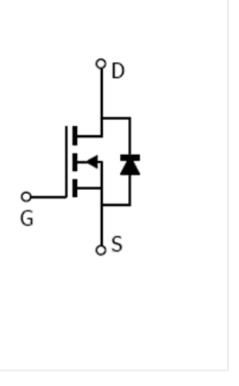
- 30V, 10.6A,  $R_{DS(ON)}=12m\Omega@V_{GS}=10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS guaranteed
- Green Device Available

#### **Applications**

- MB / VGA / Vcore
- **DC-DC Converters**
- **Power Management Functions**

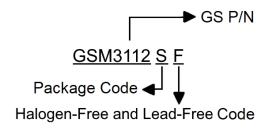
#### **Packages & Pin Assignments**





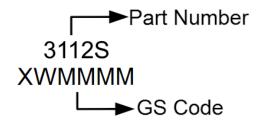


### **Ordering Information**



Part Number	Package	Quantity
GSM3112SF	SOP-8	4000pcs

## **Marking Information**



#### **Absolute Maximum Ratings**

T<sub>C</sub>=25°C Unless otherwise noted

Symbol	Parameter		Typical	Unit
$V_{DS}$	Drain-Source Voltage		30	V
V <sub>GS</sub>	Gate-Source Voltage		±20	V
	Continuous Drain Current	T <sub>A</sub> =25°C	10.6	
ID		T <sub>A</sub> =70°C	8.5	Α
		Tc=25°C	16	
I <sub>DM</sub>	Pulsed Drain Current <sup>1</sup>		40	Α
EAS	Single Pulse Avalanche Energy <sup>2</sup>		21	mJ
	Power Dissipation	T <sub>A</sub> =25°C	2.1	
P <sub>D</sub>		T <sub>A</sub> =70°C	1.4	W
		Tc=25°C	5	
TJ	Operating Junction Temperature Range		-55 to +150	$^{\circ}\mathbb{C}$
Tstg	Storage Temperature Range		-55 to +150	$^{\circ}\!\mathbb{C}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient		60	°C/W
R <sub>θJC</sub>	Thermal Resistance-Junction to Case		25	°C/W



#### **Electrical Characteristics**

#### T<sub>J</sub>=25°C Unless otherwise noted

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
		Static					
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30			V	
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1.2		2.5	V	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA	
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V			1	uA	
		V <sub>GS</sub> =10V, I <sub>D</sub> =10A		7.9	12		
R <sub>DS(on)</sub>	Drain-Source On-Resistance <sup>3</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A,		12.8	16	mΩ	
<b>g</b> FS	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =3A			9	S	
$V_{SD}$	Diode Forward Voltage <sup>3</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A		0.7	1	V	
		Dynamic					
Qg	Total Gate Charge <sup>3,4</sup>			8		nC	
Qgs	Gate-Source Charge <sup>3,4</sup>	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =12.5A		4			
$Q_{gd}$	Gate-Drain Charge <sup>3,4</sup>	10=12.5A		2		<u> </u>	
Ciss	Input Capacitance			1040			
Coss	Output Capacitance	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V, f=1MHz		445		pF	
Crss	Reverse Transfer Capacitance	1=1101112		40			
t <sub>d(on)</sub>	Turn-On Time <sup>3,4</sup>			10			
tr	Rise Time <sup>3,4</sup>	V <sub>DD</sub> =15V, I <sub>D</sub> =12.5A,		9		ns	
t <sub>d(off)</sub>	Turn-Off Time <sup>3,4</sup>	$V_{GS}=10V$ , $R_{G}=6\Omega$		24			
t <sub>f</sub>	Fall Time <sup>3,4</sup>			8			
Rg	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		1.1		Ω	

#### Note:

- 1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
- 2.  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.3mH, I<sub>AS</sub>=12A, Starting T<sub>J</sub>=25 $^{\circ}$ C.
- 3. The data tested by pulsed , pulse width  $\,\leq\,\,$  300us , duty cycle  $\,\leq\,\,$  2%.
- 4. Essentially independent of operating temperature.



#### **Typical Performance Characteristics**

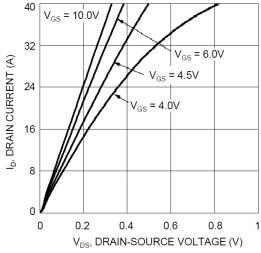


Fig. 1 Typical Output Characteristics

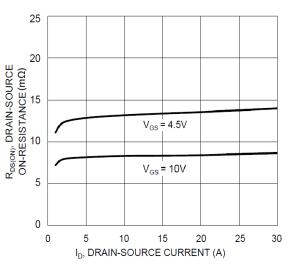


Fig. 3 Typical On-Resistance vs  $I_D$  and  $V_{GS}$ 

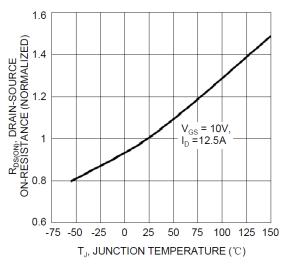


Figure. 5 On-Resistance Variation with TJ

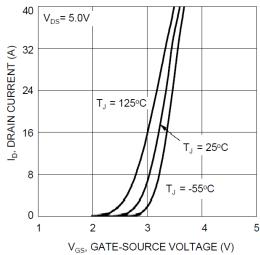


Fig. 2 Typical Transfer Characteristics

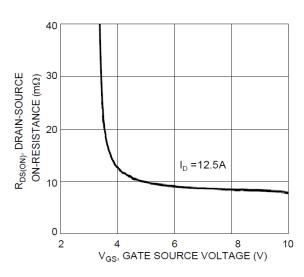


Fig. 4 Typical Transfer Characteristic

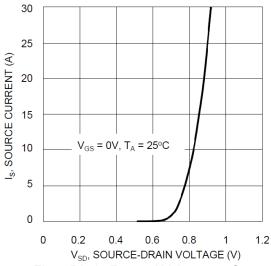


Fig. 6 Diode Forward Voltage vs. Current



# **Typical Performance Characteristics (Continue)**

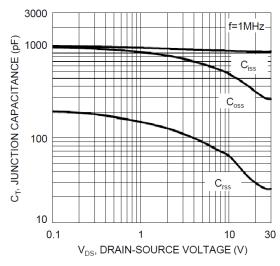


Fig. 7 Typical Capacitance

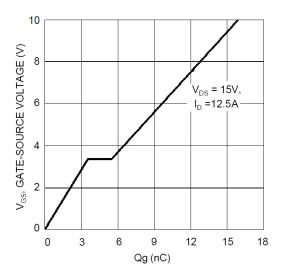
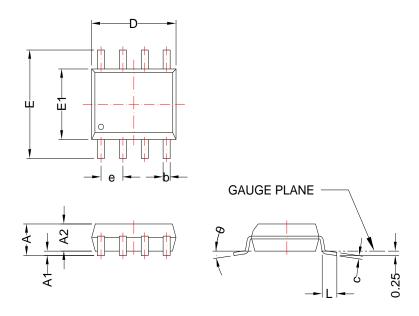


Fig. 8 Gate Charge



### **Package Dimension**

# SOP-8



DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER END.

	Dimensions				
OVMDOL	Millir	neters	Inc	hes	
SYMBOL	MIN	MAX	MIN	MAX	
Α	1.35	1.75	0.053	0.069	
<b>A</b> 1	0.10	0.25	0.004	0.010	
A2	1.25		0.049		
b	0.31	0.51	0.012	0.020	
С	0.10	0.26	0.004	0.010	
D	4.70	5.10	0.185	0.201	
E	5.80	6.20	0.228	0.244	
E1	3.70	4.10	0.146	0.161	
е	1.27 BSC		0.050	BSC	
L	0.4	1.27	0.016	0.050	
θ	0°	8°	0°	8°	



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